



503.34403CV4

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): T. MASUDA, et al

Serial No.: 09/421,043

Filed: October 20, 1999

For: PLASMA ETCHING APPARATUS AND PLASMA ETCHING METHOD

Group: 1765

Examiner: D. Deo

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AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

August 3, 2001

Sir:

The following amendments and remarks are respectfully submitted in connection with the above-identified application in response to the Office Action dated June 6, 2001.

IN THE CLAIMS:

Please cancel claims 13-20 without prejudice or disclaimer of the subject matter thereof, and add the following claims in lieu thereof:

--21. A plasma etching apparatus for etching of a sample comprising:

an etching chamber having a sidewall and an exchangeable jacket which is held inside of said sidewall so as to form a wall surface of the etching chamber, the sample being disposed